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NAME OF INVENTOR(S): Yoshino	
RECEIPT DATE & SERIAL NO.: <b>Serial No.: 10/621,771</b>	
TITLE OF INVENTION: SEMICONDUCTOR PACKAGE INSULATION FILM AND MANUFACTURING METHOD THEREOF	
FILING DATE: 7/17/2003	
TI FILE NO.: <b>TI-29448.1</b>	DEPOSIT ACCT. NO.: <b>20-0668</b>
FAXED: <b>11-29-04</b>	
DUE: 11/12/2004	
ATTY/SECY: wds/tc	

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Yoshino Docket No: TI-29448.1  
Serial No: 10/621,771 Examiner: Clark, Sheila V.  
Filed: 7/17/2003 Art Unit: 2815  
For: SEMICONDUCTOR PACKAGE INSULATION FILM AND

MANUFACTURING METHOD THEREOF

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AMENDMENT UNDER 37 C.F.R. § 1.115

Assistant Commissioner For Patents  
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Tommie Chambers

Dear Sir:

Responsive to the Office Action mailed August 12, 2004 in connection with the  
above identified application, Applicants respectfully submit the following amendments  
and remarks.

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